Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.						This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type Distribute						ials and Mfg Information					
Supplier	Information															
Company	name*	Company uni	Company unique ID			Unique ID Authority					Response Date*					
onsemi													2024-05-14			
Contact N	ame	Title - Contact				Phone - Contact*					Email - Contact*					
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorized	d Representative*	Title - Representative				Phone - Representative*				Email - Representative*						
Product-E	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number	ster Item Number Mfr Item Number		umber Mfr Item Name			Effectiv	ve Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type	
	FSUSB1			1L10X USB1.1 Switch			2024-0	5-14		TH	TH2		8.813692	mg	Each	
Manufacturing Process Information																
	Terminal Plating / Grid Array Material Te			Terminal Base Alloy J-STD-020 MSI			Peak Process Body Temperature Max Time at Pea			Max Time at Peak	x Temperature Number of Reflow Cycles					
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1			260	260 C 30		30	seconds 3					
Comments																
level 1 - maximum time at peak temperature during soldering is 10-30 seconds																
For more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard T											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.1186	mg	Supplier	Silicon (Si)	7440-21-3		2.1186	mg
Die Attach	0.016	mg	Supplier	Bis-phenol A Diglycidyl Ether	1675-54-3		0.0032	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.0096	mg
			Supplier	2,4,6-Tris[Bis(Methoxymethyl)Amino]-1,3,5-Triazine	3089-11-0		0.0032	mg
Mold Compound-Black	4.45	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.6675	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0222	mg
			Supplier	Silica (SiO2)	14464-46-1		3.7602	mg
Plating	0.02495	mg	В	Nickel (Ni)	7440-02-0		0.0205	mg
			Supplier	Gold (Au)	7440-57-5		0.0045	mg
Substrate	2.12415		Supplier	Bismaleimide	13676-54-5		1.0461	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1		0.6797	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.054	mg
			В	Nickel (Ni)	7440-02-0		0.0212	mg
			Supplier	Gold (Au)	7440-57-5		0.0045	mg
			Supplier	Copper (Cu)	7440-50-8		0.3186	mg
Wire Bond - Au	0.079992	mg	Supplier	Gold (Au)	7440-57-5		0.08	mg